


Features	Applications
<ul style="list-style-type: none"> ● Extremely small size ● Extremely fast response time ● Excellent SMD handling ● Stable performance over life ● Very low capacitance ● High insulation resistance ● Storage and operating temperature -40...+125°C ● RoHS-compatible ● UL No:E199538 	<ul style="list-style-type: none"> ● Splitter ● PCI Cards ● Morden ● Line cards 

Electrical specifications

Part Number	DC Breakdown Voltage	Max. Impulse Breakdown Voltage	Discharge Current (8/20us)	Impulse Life (10/1000us)	Minimum Insulation Resistance		Max. Capacitance 1MHz
	100V/S	1KV/us		10 times	100A	Test Voltage DC(V)	
	V	V	A	Times	(pF)		
UTC-4532-075N-B	75±30%	650	A : 1000 B : 2000 C : 3000	100	50	1	0.5
UTC-4532-091M-B	90±20%	700		100	50	1	0.5
UTC-4532-151M-B	150±20%	750		100	100	1	0.5
UTC-4532-201M-B	200±20%	750		100	100	1	0.5
UTC-4532-231M-B	230±20%	750		100	100	1	0.5
UTC-4532-301M-B	300±20%	800		100	100	1	0.5
UTC-4532-401M-B	400±20%	950		100	100	1	0.5
UTC-4532-471M-B	470±20%	1000		100	100	1	0.5
UTC-4532-601M-B	600±20%	1200		100	100	1	0.5

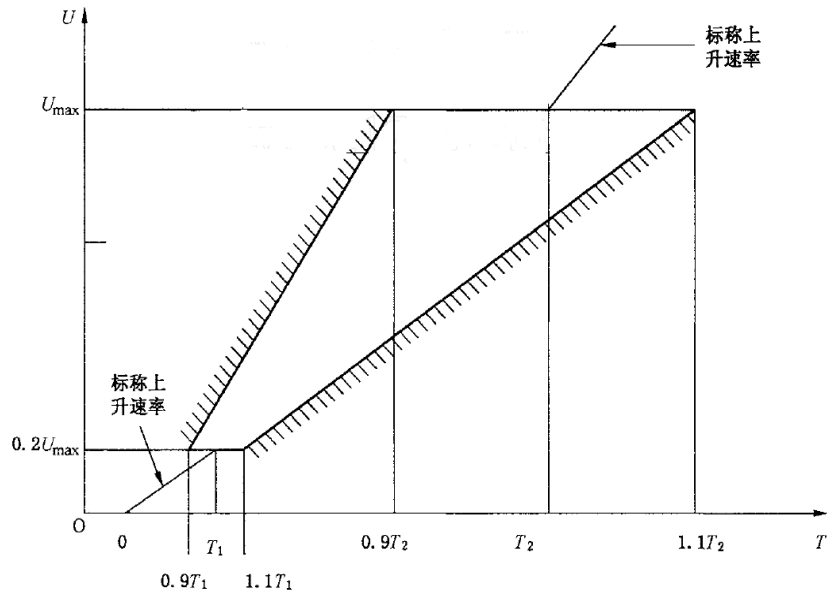
1. The parameters of all tested by ITU-T K12.
2. Total impulse discharge current 2000A@ 8/20µs by IEC 61000-4-5, 10 shots.
3. The capacitance is tested by 1MHz @DC=0.5V.

Part Number Code

UTC – 4532 – XXX M – B
(1) (2) (3) (4) (5)

- (1) Brand Name;
- (2) Series Code.
- (3) DC breakdown Voltage; e.g., 091:09X10¹=90V
- (4) Tolerance is DC breakdown voltage, L=±15%, M=±20%, N=±30%
- (5) Surge Current : (waveform 8/20µS) A : 1KA , B : 2KA , C : 3KA

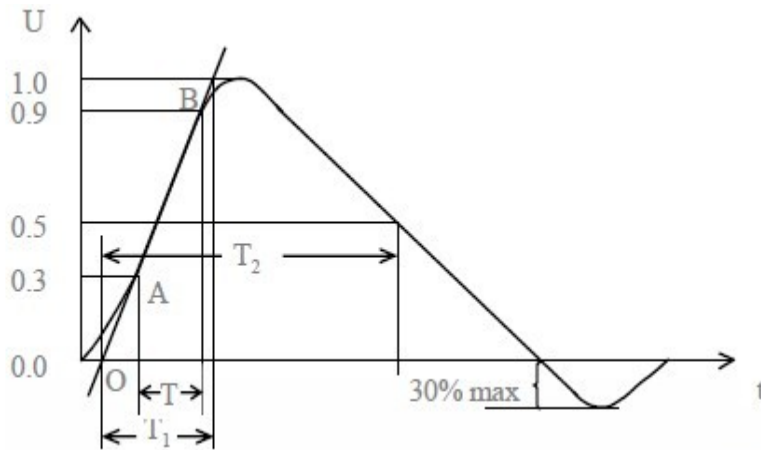
DC breakdown voltage



8/20us, Test wave
T1=1.25T=8us±20%
T2=20us±20%

10/700us, Test Wave
T1=1.67T=10us±20%
T2=700us±20%

10/1000us, Test Wave
T1=1.67T=10us±20%
T2=1000us±20%

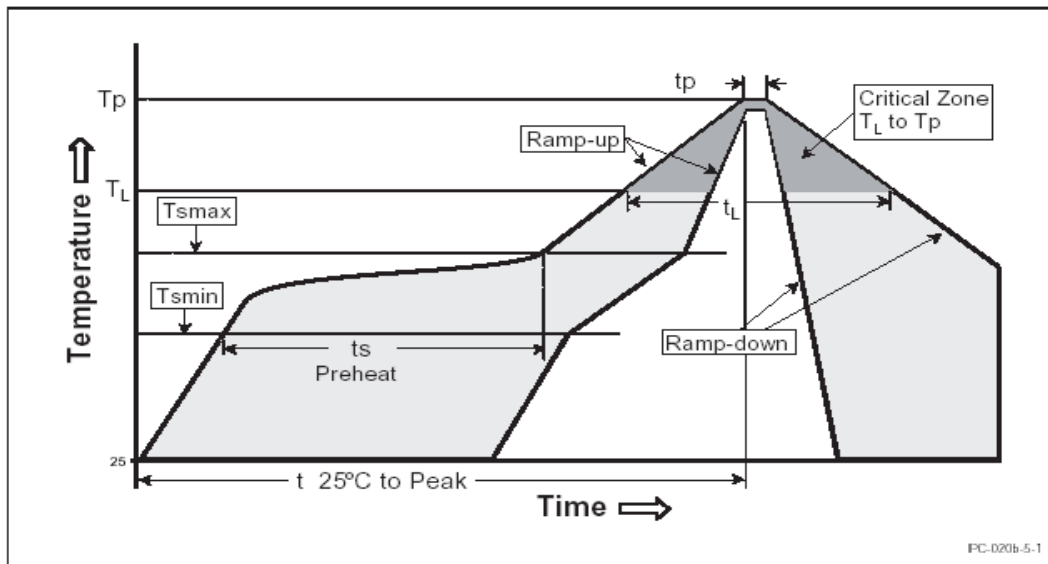


Recommended Soldering(Reflow soldering)

Soldering Method :

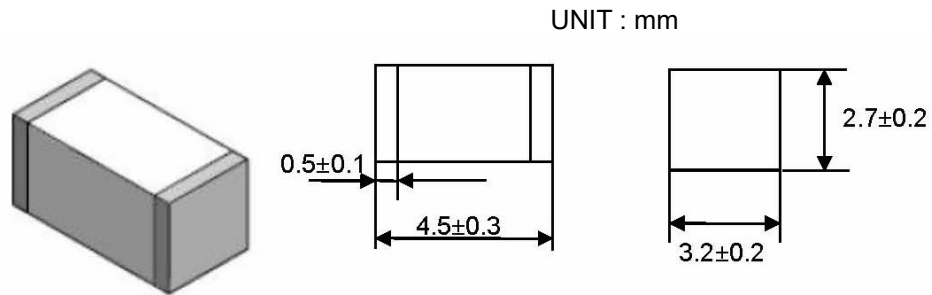
- Wave soldering : 260°C, 10 Sec. max
- Reflow soldering : 260°C, 30 Sec. max
- Hand soldering : 350°C, 3 Sec. max

Recommended Reflow Soldering Curve

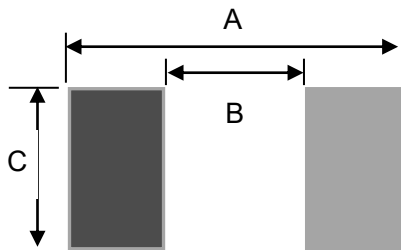


Reflow Condition		Pb-free assembly
Pre Heat	Temperature Min (T_s (min))	150°C
	Temperature Max (T_s (max))	200°C
	Time (Min to Max) (t_s)	60-180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		3°C/second max
T_s (max) to T_L -Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (t_L)	60-150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10-30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (t 25°C to peak)		8 minutes max
Do not exceed		260°C

Dimensions

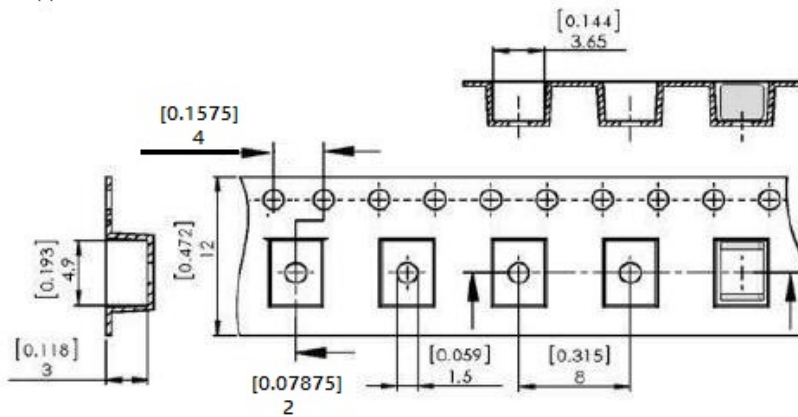


Recommended Soldering Pad



REF	mm
A	5.50
B	2.50
C	4.00

Package Reel Information



Tolerance: ±0.25mm

PACKAGING

Part Number	Component Package	Quantity
UTC-4532 Series	1812	2500